

Title (en)
LIGHTING MODULE ASSEMBLY COMPRISING AN LED ON A CIRCUIT BOARD

Title (de)
LEUCHTMODULANORDNUNG MIT EINER LED AUF EINER PLATINE

Title (fr)
SYSTEME D'ECLAIRAGE MODULAIRE COMPRENANT UNE DEL SUR UNE PLATINE

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Application
EP 11764521 A 20110926

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Abstract (en)
[origin: WO2012041795A1] The invention relates to a lighting module assembly for a luminaire. The lighting module assembly comprises at least one LED (2), at least one circuit board (4), wherein the at least one LED (2) is arranged on the at least one circuit board (4), and a carrier element (6), on which the at least one circuit board (6) is mounted. In addition, the lighting module assembly comprises at least one pressing element (8), which is arranged such that it presses the at least one circuit board (4) against a surface region of the carrier element. Because of the design comprising such a pressing element (8), no glued connection is required between the circuit board (4) and the carrier element (6). Improved thermal transfer is thus made possible between the circuit board (4) and the carrier element (6). Moreover, because of the pressing element (8) it can be achieved that the pressing force acting on the circuit board (4) is uniformly maintained over the course of the service life of the lighting module assembly such that a decrease of the quality of the thermal contact can virtually be excluded or can at least be significantly reduced as compared to the prior art.

IPC 8 full level
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Citation (opposition)
Opponent : ITZ Innovations- und Technologiezentrum GmbH
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• US 2007098334 A1 20070503 - CHEN KUEI-FANG [TW]
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